ORDERING INFORMATION

Temp Range	Package	Part Number
DG417B, DG418B		
- 40 °C to 85 °C	8-Pin Plastic MiniDIP	DG417BDJ DG417BDJ-E3
		DG418BDJ DG418BDJ-E3
	8-Pin Narrow SOIC	DG417BDY DG417BDY-E3 DG417BDY-T1 DG417BDY-T1-E3
		DG418BDY DG418BDY-E3 DG418BDY-T1 DG418BDY-T1-E3
	8-Pin MSOP	DG417BDQ-T1-E3
		DG418BDQ-T1-E3
DG419B		
- 40 °C to 85 °C	8-Pin Plastic MiniDIP	DG419BDJ DG419BDJ-E3
	8-Pin Narrow SOIC	DG419BDY DG419BDY-E3 DG419BDY-T1 DG419BDY-T1-E3
	8-Pin MSOP	DG419BDQ-T1-E3

ABSOLUTE MAXIMUM RATINGS

Parameter		Limit	Unit
V-		- 20	V
V+		20	
GND		25	
V_L		(GND - 0.3) to (V+) + 0.3	
Digital Inputs[a], V_S, V_D		(V-) - 2 V to (V+) + 2 or 30 mA, whichever occurs first	
Current, (Any Terminal) Continuous		30	mA
Current (S or D) Pulsed at 1 ms, 10 % Duty Cycle		100	
Storage Temperature		- 65 to 150	°C
Power Dissipation (Package)[b]	8-Pin Plastic MiniDIP[c]	400	mW
	8-Pin Narrow SOIC[c]	400	
	8-Pin MSOP[d]	400	
	8-Pin CerDIP[e]	600	

Notes:
a. Signals on S_X, D_X, or IN_X exceeding V+ or V- will be clamped by internal diodes. Limit forward diode current to maximum current ratings.
b. All leads welded or soldered to PC board.
c. Derate 5.3 mW/°C above 75 °C.
d. Derate 4 mW/°C above 70 °C.
e. Derate 8 mW/°C above 75 °C.

SCHEMATIC DIAGRAM Typical Channel

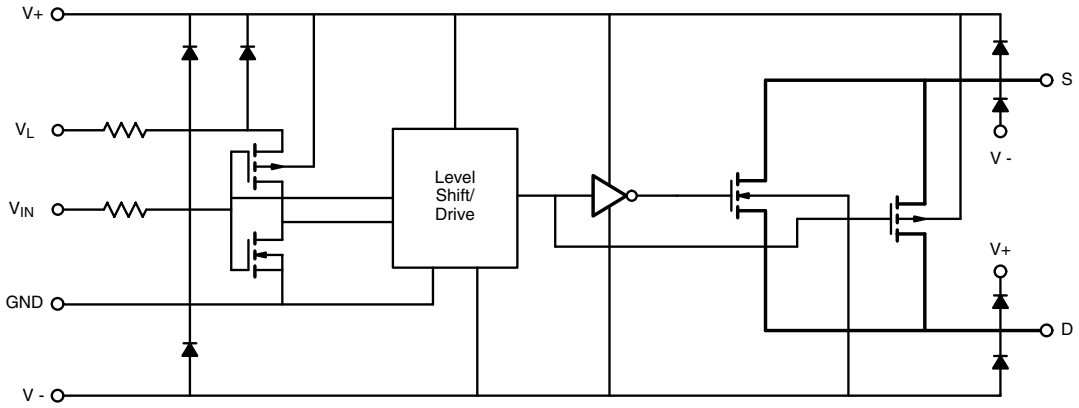


Figure 1.

SPECIFICATIONS[a]

Parameter	Symbol	Test Conditions Unless Otherwise Specified V+ = 15 V, V- = - 15 V V_L = 5 V, V_{IN} = 2.4 V, 0.8 V[f]		Temp.[b]	Typ.[c]	A Suffix - 55 °C to 125 °C Min.[d]	A Suffix - 55 °C to 125 °C Max.[d]	D Suffix - 40 °C to 85 °C Min.[d]	D Suffix - 40 °C to 85 °C Max.[d]	Unit
Analog Switch										
Analog Signal Range[e]	V_{ANALOG}			Full		- 15	15	- 15	15	V
Drain-Source On-Resistance	$R_{DS(on)}$	I_S = - 10 mA, V_D = ± 12.5 V V+ = 13.5 V, V- = - 13.5 V		Room Full	15		25 34		25 29	Ω
Switch Off Leakage Current	$I_{S(off)}$	V+ = 16.5, V- = - 16.5 V V_D = ± 15.5 V, V_S = ± 15.5 V		Room Full	- 0.1	- 0.25 - 20	0.25 20	- 0.25 - 5	0.25 5	nA
	$I_{D(off)}$		DG417B DG418B	Room Full	- 0.1	- 0.25 - 20	0.25 20	- 0.25 - 5	0.25 5	
			DG419B	Room Full	- 0.1	- 0.75 - 60	0.75 60	- 0.75 - 12	0.75 12	
Channel On Leakage Current	$I_{D(on)}$	V+ = 16.5 V, V- = - 16.5 V V_S = V_D = ± 15.5 V	DG417B DG418B	Room Full	- 0.4	- 0.4 - 40	0.4 40	- 0.4 - 10	0.4 10	
			DG419B	Room Full	- 0.4	- 0.75 - 60	0.75 60	- 0.75 - 12	0.75 12	
Digital Control										
Input Current, V_{IN} Low	I_{IL}			Full		- 0.5	0.5	- 0.5	0.5	µA
Input Current, V_{IN} High	I_{IH}			Full		- 0.5	0.5	- 0.5	0.5	
Dynamic Characteristics										
Turn-On Time	t_{ON}	R_L = 300 Ω, C_L = 35 pF V_S = ± 10 V, See Switching Time Test Circuit	DG417B DG418B	Room Full	62		89 106		89 99	ns
Turn-Off Time	t_{OFF}		DG417B DG418B	Room Full	53		80 88		80 86	
Transition Time	t_{TRANS}	R_L = 300 Ω, C_L = 35 pF V_{S1} = ± 10 V, V_{S2} = ± 10 V	DG419B	Room Full	60		87 96		87 93	
Break-Before-Make Time Delay	t_D	R_L = 300 Ω, C_L = 35 pF V_{S1} = V_{S2} = ± 10 V	DG419B	Room	16	3		3		
Charge Injection	Q	C_L = 10 nF V_{gen} = 0 V, R_{gen} = 0 Ω		Room	38					pC
Off Isolation[e]	OIRR	R_L = 50 Ω, C_L = 5 pF, f = 1 MHz		Room	- 82					dB
Channel-to-Channel Crosstalk[e]	X_{TALK}		DG419B	Room	- 88					

SPECIFICATIONS[a]

Parameter	Symbol	Test Conditions Unless Otherwise Specified V+ = 15 V, V- = - 15 V V_L = 5 V, V_{IN} = 2.4 V, 0.8 V[f]		Temp.[b]	Typ.[c]	A Suffix - 55 °C to 125 °C Min.[d]	A Suffix - 55 °C to 125 °C Max.[d]	D Suffix - 40 °C to 85 °C Min.[d]	D Suffix - 40 °C to 85 °C Max.[d]	Unit
Dynamic Characteristics										
Source Off Capacitance[e]	$C_{S(off)}$	f = 1 MHz, V_S = 0 V		Room	12					pF
Drain Off Capacitance[e]	$C_{D(off)}$	f = 1 MHz, V_S = 0 V	DG417B DG418B	Room	12					pF
Channel On Capacitance[e]	$C_{D(on)}$	f = 1 MHz, V_S = 0 V	DG417B DG418B	Room	50					pF
			DG419B	Room	57					pF
Power Supplies										
Positive Supply Current	I+	V+ = 16.5 V, V- = - 16.5 V V_{IN} = 0 or 5 V		Room Full	0.001		1 5		1 5	µA
Negative Supply Current	I-			Room Full	- 0.001	- 1 - 5		- 1 - 5		µA
Logic Supply Current	I_L			Room Full	0.001		1 5		1 5	µA
Ground Current	I_{GND}			Room Full	- 0.001	- 1 - 5		- 1 - 5		µA

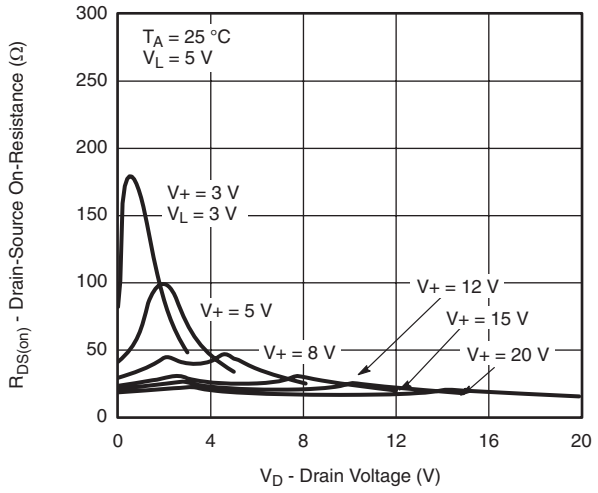
SPECIFICATIONS[a]

Parameter	Symbol	Test Conditions Unless Otherwise Specified V+ = 12 V, V- = 0 V V_L = 5 V, V_{IN} = 2.4 V, 0.8 V[f]		Temp.[b]	Typ.[c]	A Suffix - 55 °C to 125 °C Min.[d]	A Suffix - 55 °C to 125 °C Max.[d]	D Suffix - 40 °C to 85 °C Min.[d]	D Suffix - 40 °C to 85 °C Max.[d]	Unit
Analog Switch										
Analog Signal Range[e]	V_{ANALOG}			Full		0	12	0	12	V
Drain-Source On-Resistance	$R_{DS(on)}$	I_S = - 10 mA, V_D = 3.8 V V+ = 10.8 V		Room Full	26		35 52		35 45	Ω
Dynamic Characteristics										
Turn-On Time	t_{ON}	R_L = 300 Ω, C_L = 35 pF V_S = 8 V, See Switching Time Test Circuit		Room Full	100		125 155		125 143	ns
Turn-Off Time	t_{OFF}			Room Full	38		66 73		66 69	ns
Break-Before-Make Time Delay	t_D	R_L = 300 Ω, C_L = 35 pF	DG419B	Room	62	25		25		ns
Transition Time	t_{TRANS}	R_L = 300 Ω, C_L = 35 pF V_{S1} = 0 V, 8 V, V_{S2} = 8 V, 0 V		Room Full	95		119 153		119 141	ns
Charge Injection	Q	C_L = 10 nF, V_{gen} = 0 V, R_{gen} = 0 Ω		Room	18					pC
Power Supplies										
Positive Supply Current	I+	V+ = 13.2 V, V_L = 5.25 V V_{IN} = 0 or 5 V		Room Full	0.001		1 5		1 5	µA
Negative Supply Current	I-			Room	- 0.001	- 1 - 5		- 1 - 5		µA
Logic Supply Current	I_L			Room	0.001		1 5		1 5	µA
Ground Current	I_{GND}			Room	- 0.001	- 1 - 5		-1 - 5		µA

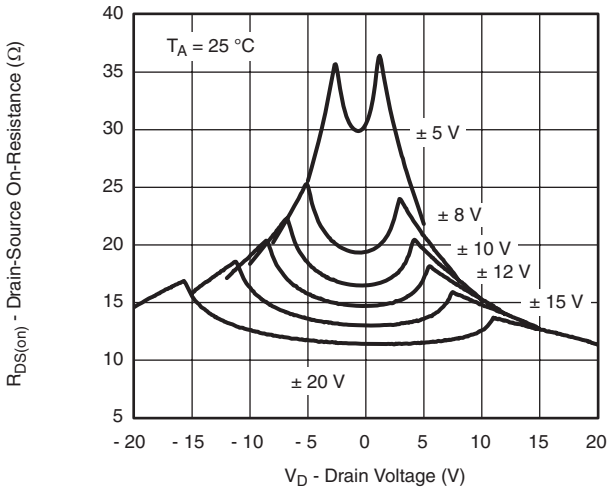
Notes:
a. Refer to PROCESS OPTION FLOWCHART.
b. Room = 25 °C, full = as determined by the operating temperature suffix.
c. Typical values are for DESIGN AID ONLY, not guaranteed nor subject to production testing.
d. The algebraic convention whereby the most negative value is a minimum and the most positive a maximum, is used in this datasheet.
e. Guaranteed by design, not subject to production test.
f. V_{IN} = input voltage to perform proper function.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

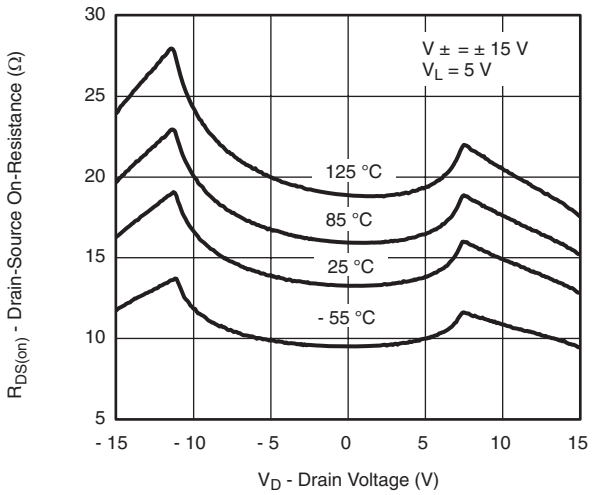
TYPICAL CHARACTERISTICS T_A = 25 °C, unless otherwise noted



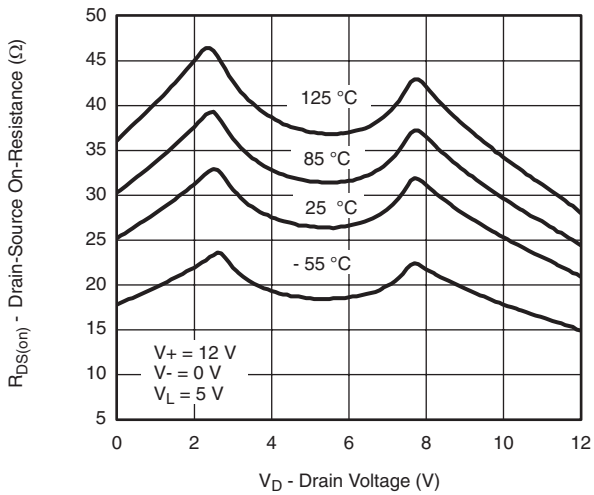
On-Resistance vs. V_D and Unipolar Power Supply Voltage



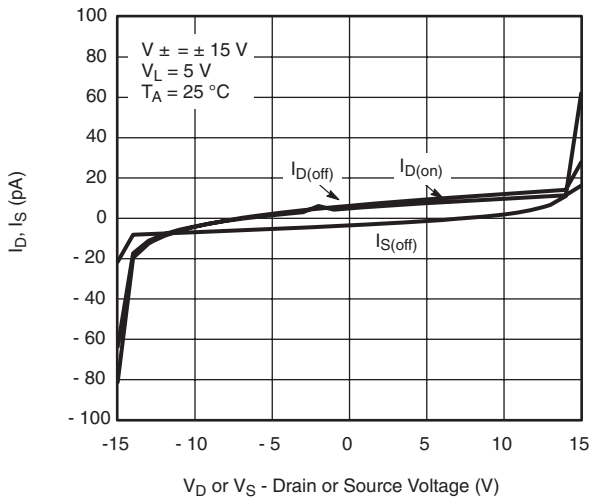
On-Resistance vs. V_D and Dual Supply Voltage



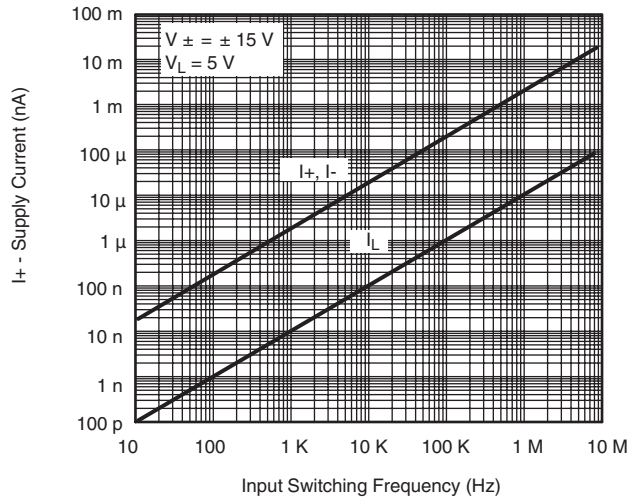
On-Resistance vs. V_D and Temperature



On-Resistance vs. V_D and Temperature

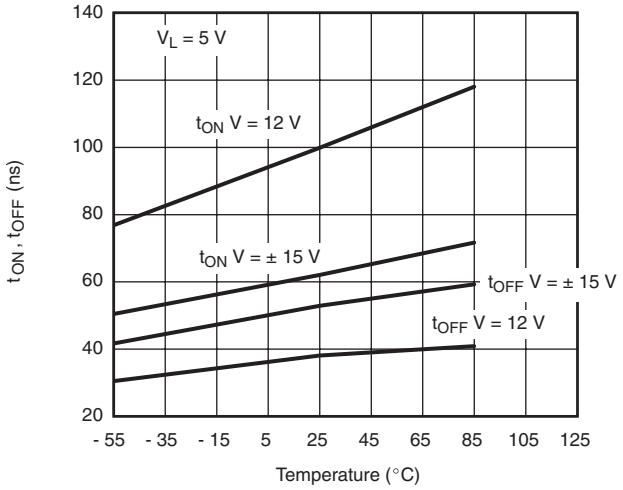


Leakage vs. Analog Voltage

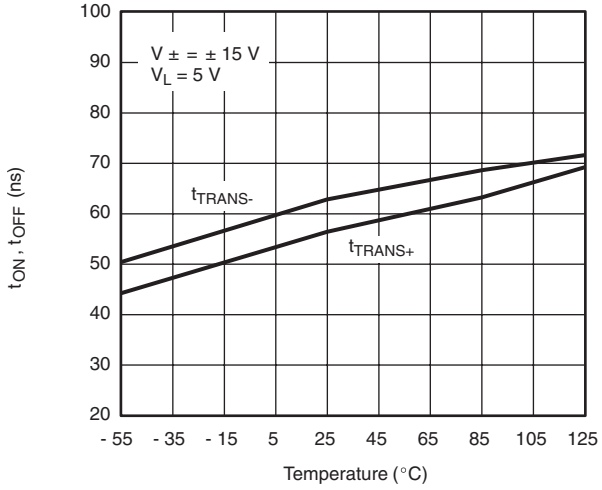


Supply Current vs. Input Switching Frequency

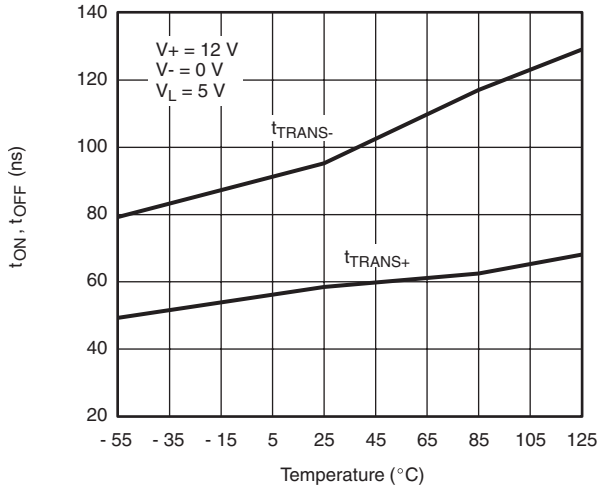
TYPICAL CHARACTERISTICS T_A = 25 °C, unless otherwise noted



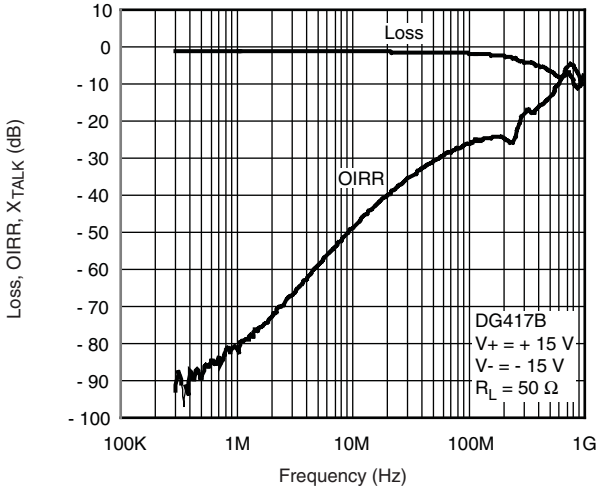
Switching Time vs. Temperature



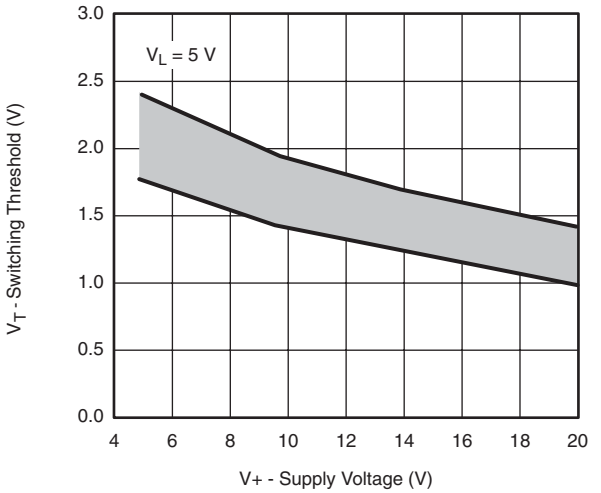
Transition Time vs. Temperature



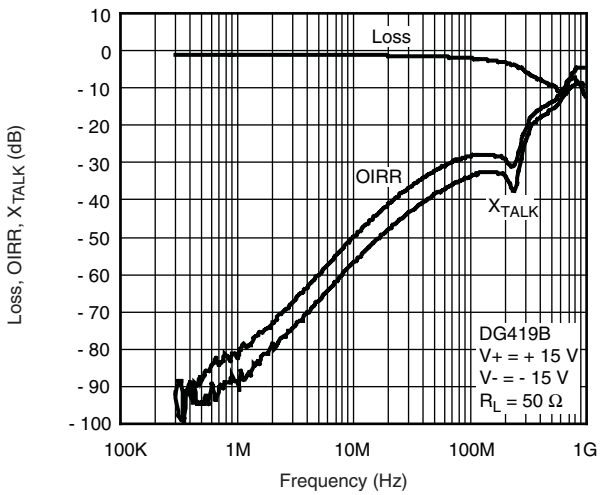
Transition Time vs. Temperature



Insertion Loss, Off -Isolation Crosstalk vs. Frequency

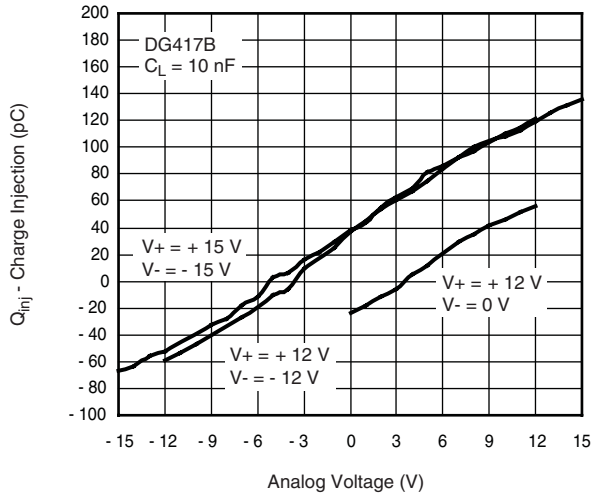


Switching Threshold vs. Supply Voltage

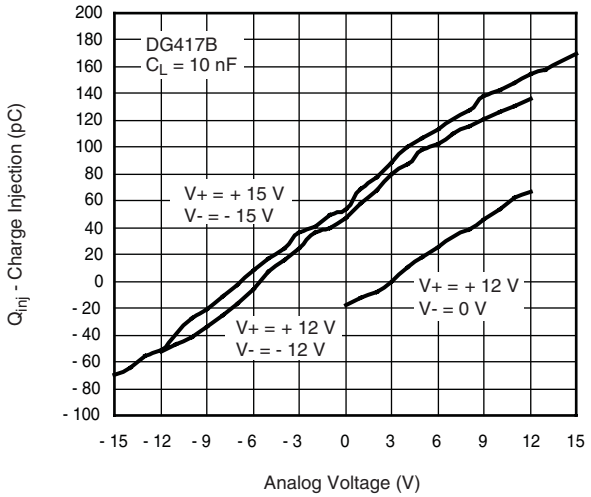


Insertion Loss, Off -Isolation Crosstalk vs. Frequency

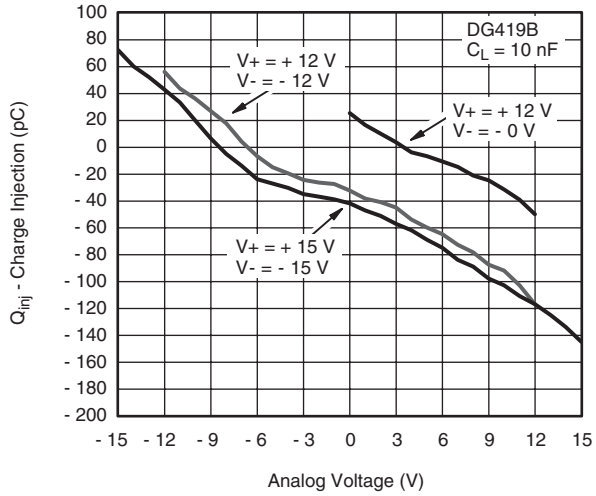
TYPICAL CHARACTERISTICS T_A = 25 °C, unless otherwise noted



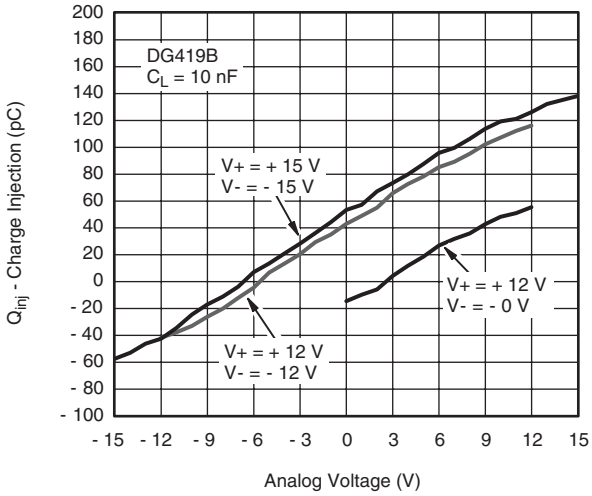
Charge Injection vs. Analog Voltage (Measured at drain pin)



Charge Injection vs. Analog Voltage (Measured at source pin)



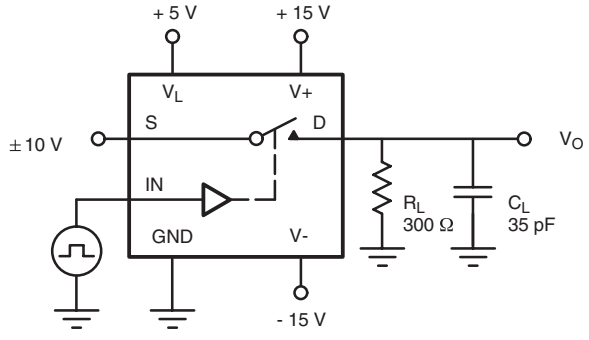
Charge Injection vs. Analog Voltage (Measured at drain pin)



Charge Injection vs. Analog Voltage (Measured at source pin)

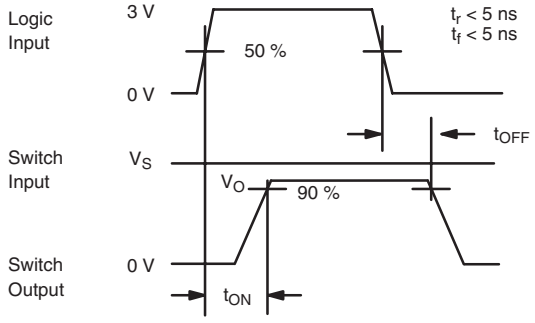
TEST CIRCUITS

V_O is the steady state output with the switch on.



C_L (includes fixture and stray capacitance)

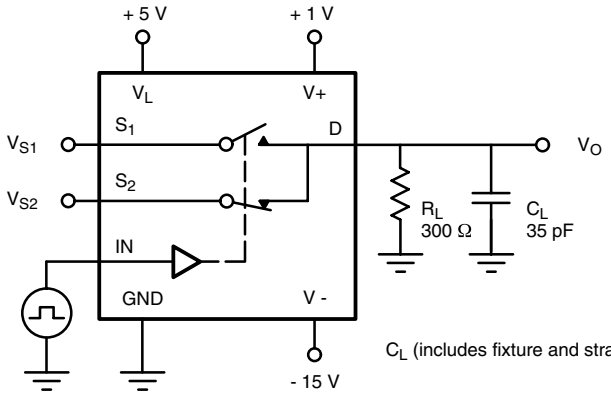
$$V_O = V_S \frac{R_L}{R_L + R_{DS(on)}}$$



Note: Logic input waveform is inverted for switches that have the opposite logic sense.

Figure 2. Switching Time (DG417B/418B)

TEST CIRCUITS



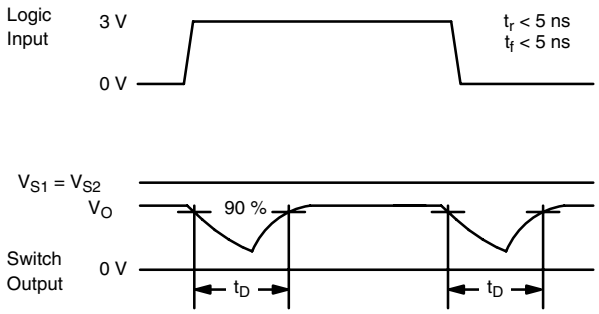
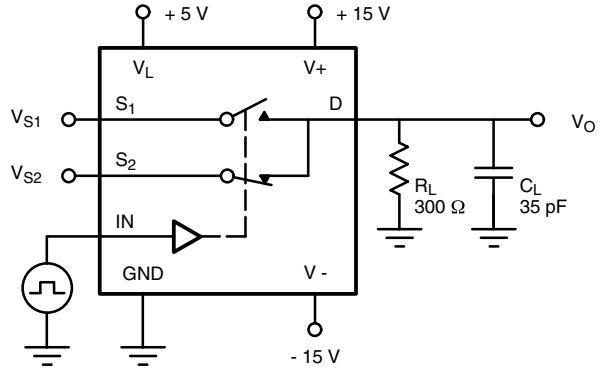


Figure 3. Break-Before-Make (DG419B)



$$V_O = V_S \frac{R_L}{R_L + r_{DS(on)}}$$

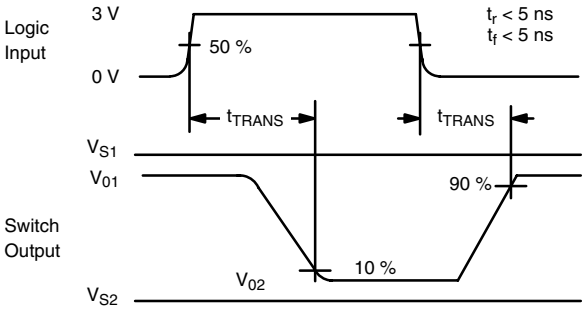
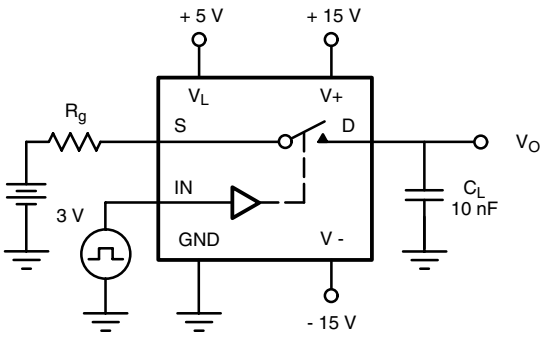
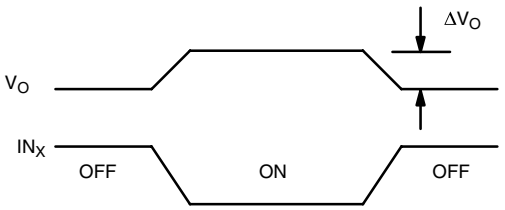


Figure 4. Transition Time (DG419B)





$$Q = \Delta V_O \times C_L$$

Figure 5. Charge Injection

TEST CIRCUITS

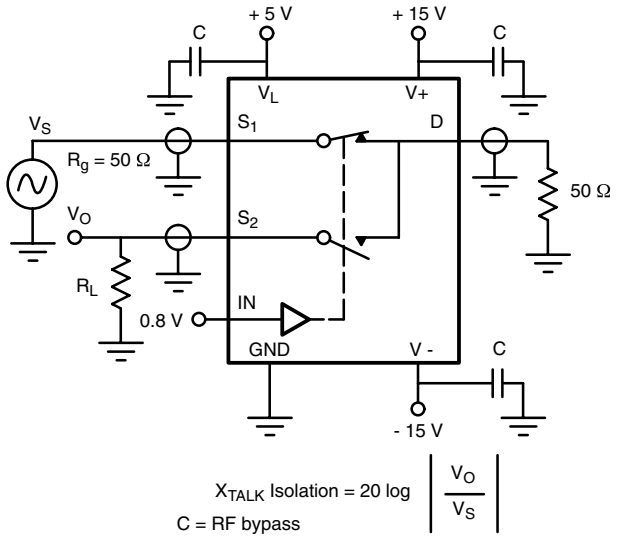


Figure 6. Crosstalk

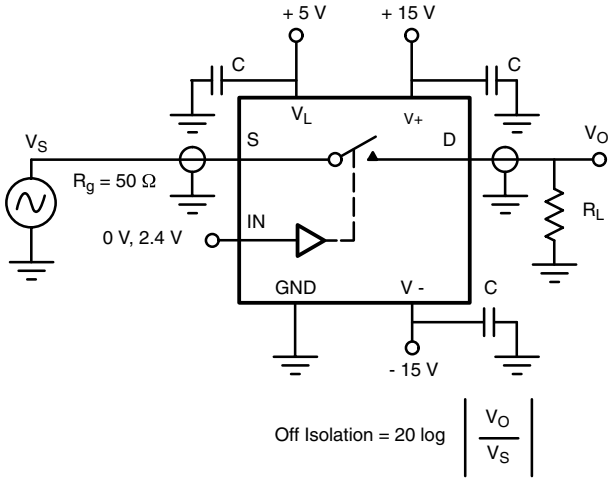


Figure 7. Off isolation

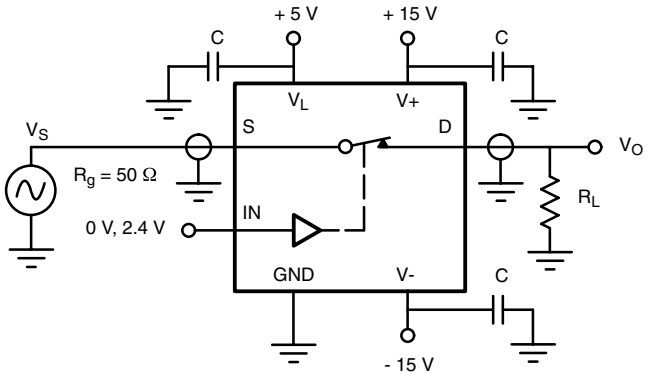


Figure 8. Insertion Loss

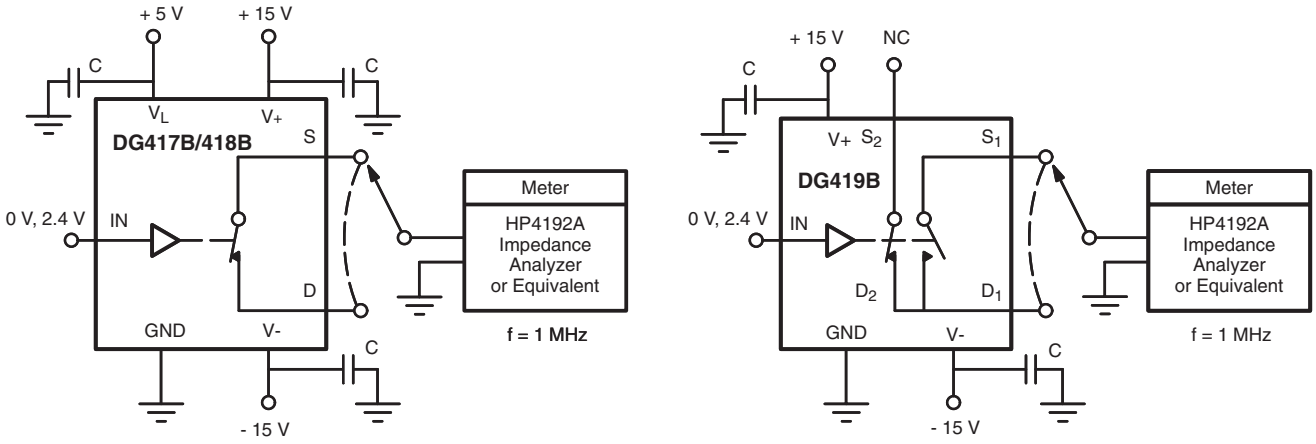
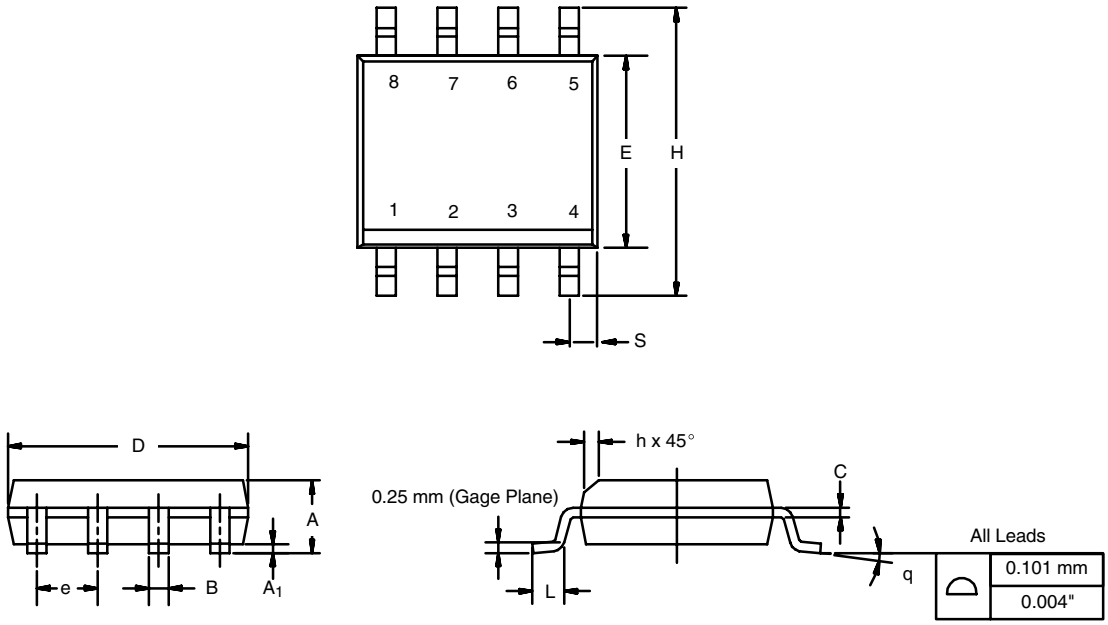


Figure 9. Source/Drain Capacitances

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?72107.

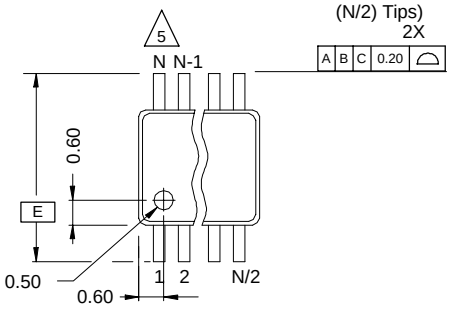
SOIC (NARROW): 8-LEAD
JEDEC Part Number: MS-012



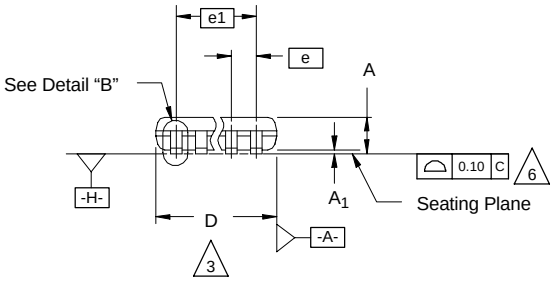
DIM	MILLIMETERS		INCHES	
	Min	Max	Min	Max
A	1.35	1.75	0.053	0.069
A_1	0.10	0.20	0.004	0.008
B	0.35	0.51	0.014	0.020
C	0.19	0.25	0.0075	0.010
D	4.80	5.00	0.189	0.196
E	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.020
L	0.50	0.93	0.020	0.037
q	0°	8°	0°	8°
S	0.44	0.64	0.018	0.026
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498				

MSOP: 8-LEADS

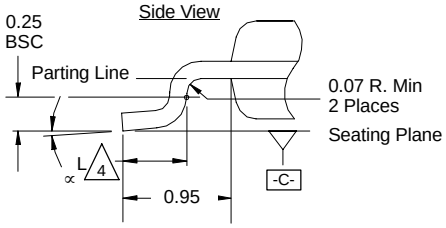
JEDEC Part Number: MO-187, (Variation AA and BA)



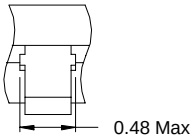
Top View



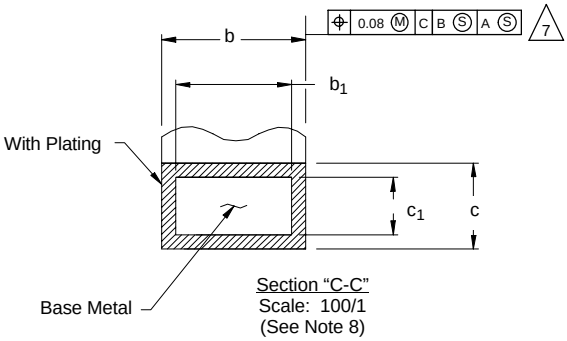
Side View



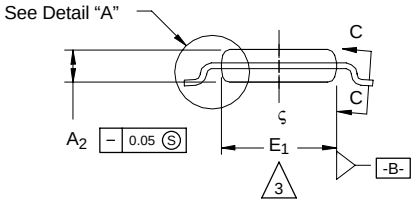
Detail "A"
(Scale: 30/1)



Detail "B"
(Scale: 30/1)
Dambar Protrusion



Section "C-C"
Scale: 100/1
(See Note 8)



End View

NOTES:

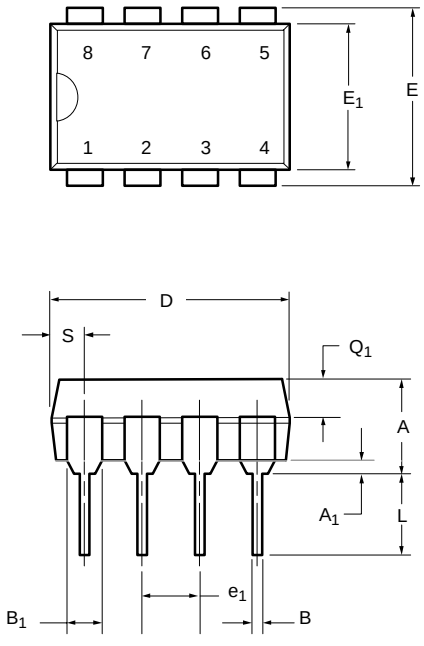
1. Die thickness allowable is 0.203 ± 0.0127.
2. Dimensioning and tolerances per ANSI.Y14.5M-1994.
3. Dimensions "D" and "E_1" do not include mold flash or protrusions, and are measured at Datum plane -H- , mold flash or protrusions shall not exceed 0.15 mm per side.
4. Dimension is the length of terminal for soldering to a substrate.
5. Terminal positions are shown for reference only.
6. Formed leads shall be planar with respect to one another within 0.10 mm at seating plane.
7. The lead width dimension does not include Dambar protrusion. Allowable Dambar protrusion shall be 0.08 mm total in excess of the lead width dimension at maximum material condition. Dambar cannot be located on the lower radius or the lead foot. Minimum space between protrusions and an adjacent lead to be 0.14 mm. See detail "B" and Section "C-C".
8. Section "C-C" to be determined at 0.10 mm to 0.25 mm from the lead tip.
9. Controlling dimension: millimeters.
10. This part is compliant with JEDEC registration MO-187, variation AA and BA.
11. Datums -A- and -B- to be determined Datum plane -H- .
12. Exposed pad area in bottom side is the same as teh leadframe pad size.

N = 8L

Dim	MILLIMETERS			Note
	Min	Nom	Max	
A	-	-	1.10	
A_1	0.05	0.10	0.15	
A_2	0.75	0.85	0.95	
b	0.25	-	0.38	8
b_1	0.25	0.30	0.33	8
c	0.13	-	0.23	
c_1	0.13	0.15	0.18	
D	3.00 BSC			3
E	4.90 BSC			
E_1	2.90	3.00	3.10	3
e	0.65 BSC			
e_1	1.95 BSC			
L	0.40	0.55	0.70	4
N	8			5
∝	0°	4°	6°	

ECN: T-02080—Rev. C, 15-Jul-02
DWG: 5867

PDIP: 8-LEAD

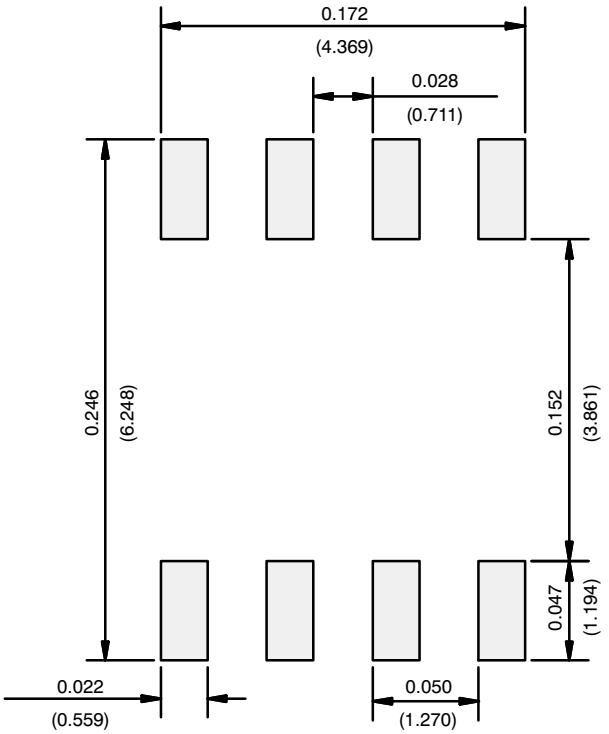


Dim	MILLIMETERS		INCHES	
	Min	Max	Min	Max
A	3.81	5.08	0.150	0.200
A_1	0.38	1.27	0.015	0.050
B	0.38	0.51	0.015	0.020
B_1	0.89	1.65	0.035	0.065
C	0.20	0.30	0.008	0.012
D	9.02	10.92	0.355	0.430
E	7.62	8.26	0.300	0.325
E_1	5.59	7.11	0.220	0.280
e_1	2.29	2.79	0.090	0.110
e_A	7.37	7.87	0.290	0.310
L	2.79	3.81	0.110	0.150
Q_1	1.27	2.03	0.050	0.080
S	0.76	1.65	0.030	0.065

ECN: S-03946—Rev. E, 09-Jul-01
DWG: 5478

NOTE: End leads may be half leads.

RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads
Dimensions in Inches/(mm)

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